NOV 3 0 2005

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of:

Chad A. Cobbley et al.

Prior Application Serial No.: -10/672,750

Prior Application Filed:

September 25, 2003

Serial No.: 10/770,919

Filed:

February 3, 2004

For: STACKED DIE MODULE AND

TECHNIQUES FOR FORMING A

STACKED DIE MODULE

Group Art Unit:

2813

Examiner:

Blum, David S.

Atty Docket: MICS:0078—5 (FLE)

(01-0752.005)

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 CERTIFICATE OF MAILING 37 C.F.R. 1.8

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA

22313-1450, on the date below:

November 28, 2005

Date

Sir:

## **RESPONSE TO OFFICE ACTION MAILED OCTOBER 27, 2005**

In response to the Office Action mailed October 27, 2005, please amend the aboveidentified application as follows: